

## **In the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A pre-clean chamber ~~for pre-cleaning a surface prior to metallization of the surface~~, comprising:

a chamber having a chamber interior;

a wafer heating apparatus ~~provided~~ in said chamber interior for supporting and heating a wafer, comprising a trench and via sidewalls etched in a dielectric layer thereon, for pre-cleaning the trench and the via sidewalls of the wafer prior to disposition of a layer thereon; and

a source RF power supply operably engaging said chamber for applying source RF energy to said chamber.

2. (original) The pre-clean chamber of claim 1 further comprising a controller operably engaging said wafer heating apparatus for controlling a temperature of said wafer heating apparatus.

3. (original) The pre-clean chamber of claim 1 further comprising a bias RF power supply operably connected to said wafer heating apparatus for applying bias RF power to said wafer heating apparatus.

4. (original) The pre-clean chamber of claim 3 further comprising a controller operably engaging said wafer heating apparatus for controlling a temperature of said wafer heating apparatus.

5. (currently amended) A pre-clean chamber ~~for pre-cleaning a surface prior to metallization of the surface~~, comprising:

a chamber having a chamber interior;

a high-temperature electrostatic chuck ~~provided~~ in said chamber interior for supporting and heating a wafer, comprising a trench and via sidewalls etched in a dielectric layer thereon, for pre-cleaning the trench and the via sidewalls of the wafer prior to disposition of a layer thereon; and

a source RF power supply operably engaging said chamber for applying source RF energy to said chamber.

6. (original) The pre-clean chamber of claim 5 further comprising a controller operably engaging said chuck for controlling a temperature of said chuck.

7. (original) The pre-clean chamber of claim 5 further comprising a bias RF power supply operably connected to said chuck for applying bias RF power to said chuck.

8. (original) The pre-clean chamber of claim 7 further comprising a controller operably engaging said chuck for controlling a temperature of said chuck.